### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
KPT-3216SGD	Super Bright Green (GaP)	Green Diffused	3	8	120°

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
   Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	I=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	I=20mA
IR	Reverse Current	Super Bright Green		10	uA	V <sub>R</sub> =5V

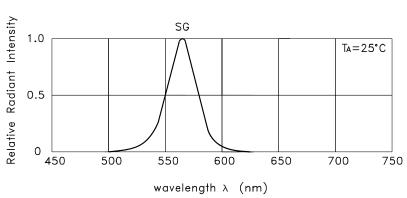
- 1.Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
   Wavelength value is traceable to the CIE127-2007 compliant national standards.

### Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

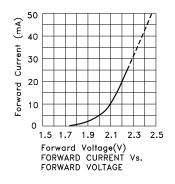
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

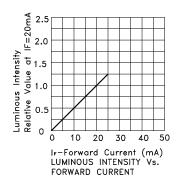
DATE: JUN/27/2012 SPEC NO: DSAA4304 **REV NO: V.9B** PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.Cui ERP: 1203001969

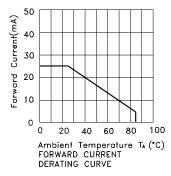


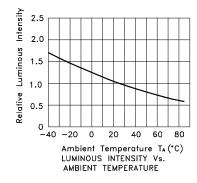
RELATIVE INTENSITY Vs. WAVELENGTH

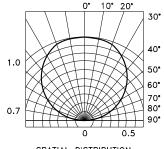
Super Bright Green KPT-3216SGD











SPATIAL DISTRIBUTION

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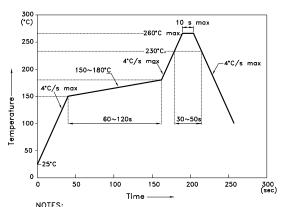
DRAWN: F.Cui

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#### **KPT-3216SGD**

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

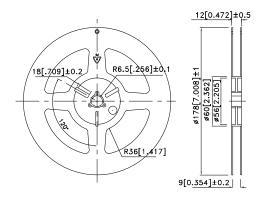
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

  3.Number of reflow process shall be 2 times or less.

## Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

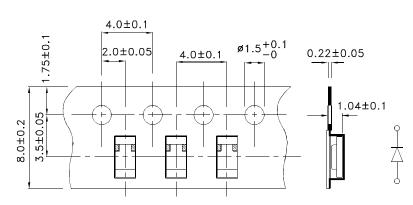
# 1.75 2.0 1.75

#### **Reel Dimension**

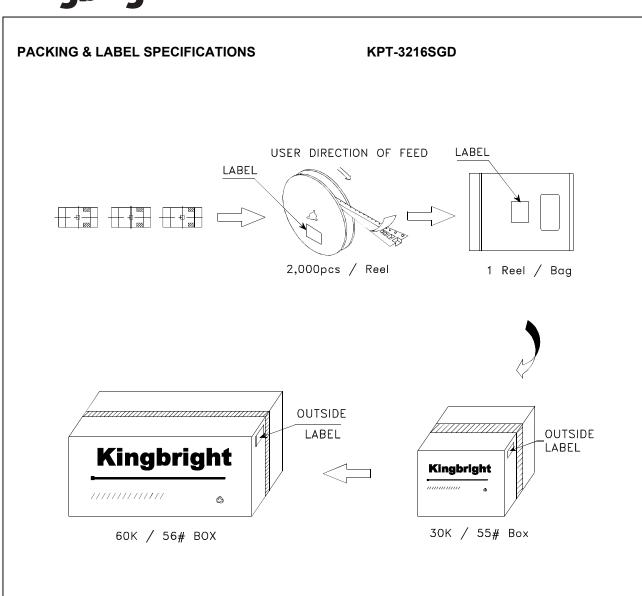


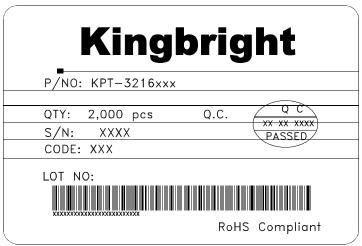
Tape Dimensions (Units : mm)

TAPE



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